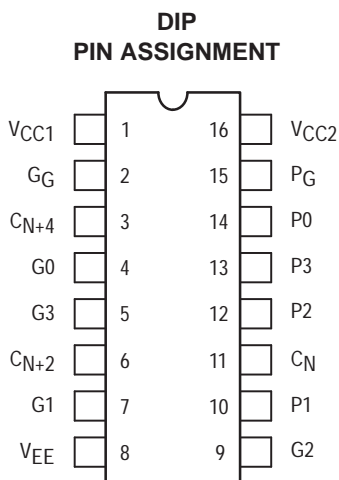


MC10H179

Look-Ahead Carry Block

The MC10H179 is a functional/pinout duplication of the standard MECL 10K part, with 100% improvement in propagation delay and no increase in power supply current.

- Power Dissipation, 300 mW Typical
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K-Compatible

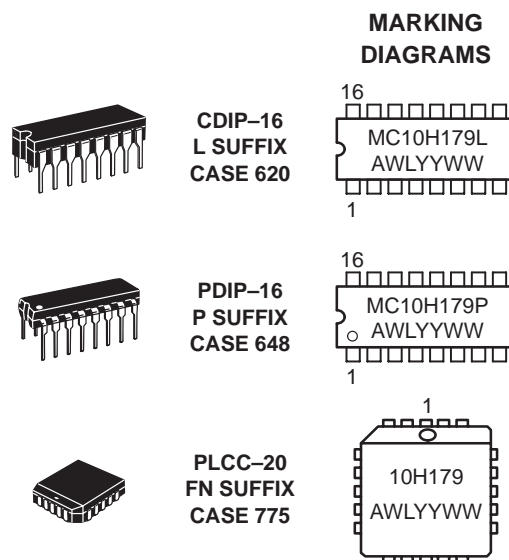


Pin assignment is for Dual-in-Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



ON Semiconductor

<http://onsemi.com>



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC10H179L	CDIP-16	25 Units/Rail
MC10H179P	PDIP-16	25 Units/Rail
MC10H179FN	PLCC-20	46 Units/Rail

MC10H179

MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
V_{EE}	Power Supply ($V_{CC} = 0$)	-8.0 to 0	Vdc
V_I	Input Voltage ($V_{CC} = 0$)	0 to V_{EE}	Vdc
I_{out}	Output Current – Continuous – Surge	50 100	mA
T_A	Operating Temperature Range	0 to +75	°C
T_{stg}	Storage Temperature Range – Plastic – Ceramic	-55 to +150 -55 to +165	°C °C

ELECTRICAL CHARACTERISTICS ($V_{EE} = -5.2\text{ V} \pm 5\%$) (See Note 1.)

Symbol	Characteristic	0°		25°		75°		Unit
		Min	Max	Min	Max	Min	Max	
I_E	Power Supply Current	–	79	–	72	–	79	mA
I_{inH}	Input Current High Pins 5 and 9	–	465	–	275	–	275	μA
	Pins 4, 7 and 11	–	545	–	320	–	320	
	Pin 14	–	705	–	415	–	415	
	Pin 12	–	790	–	465	–	465	
	Pins 10 and 13	–	870	–	510	–	510	
I_{inL}	Input Current Low	0.5	–	0.5	–	0.3	–	μA
V_{OH}	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
V_{OL}	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
V_{IH}	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V_{IL}	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

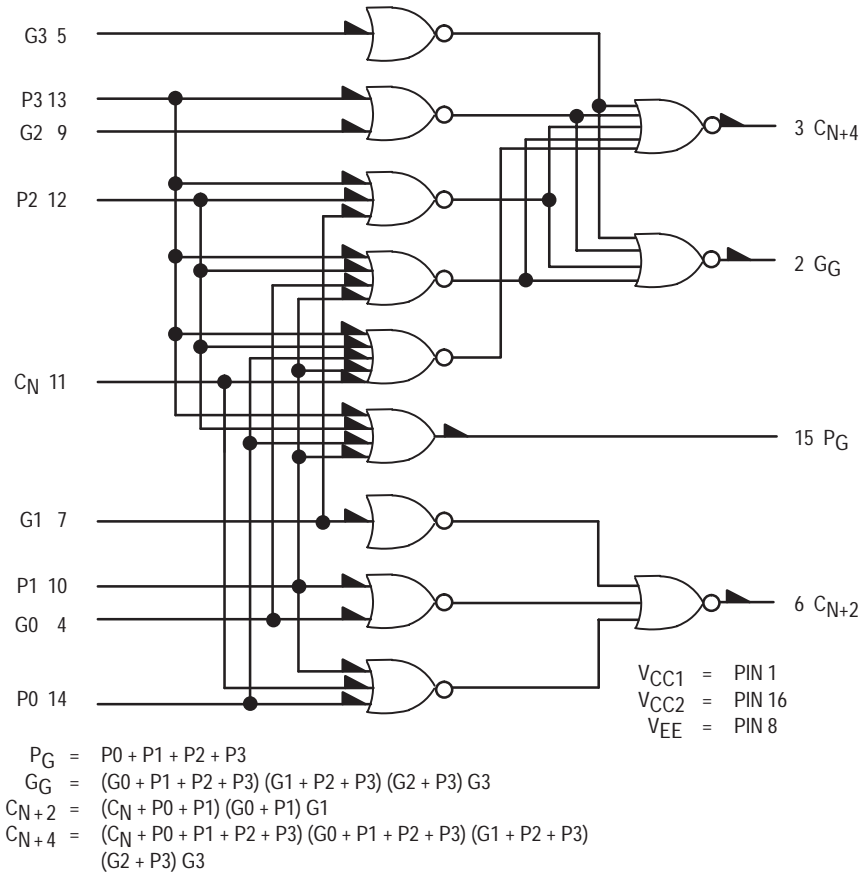
AC PARAMETERS

t_{pd}	Propagation Delay P to P_G G, P, C_N to C_N or G_G	0.4	1.4	0.4	1.5	0.5	1.7	ns
		0.6	2.3	0.7	2.4	0.8	2.6	
t_r	Rise Time	0.5	1.7	0.5	1.8	0.5	1.9	ns
t_f	Fall Time	0.5	1.7	0.5	1.8	0.5	1.9	ns

- Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts.

MC10H179

LOGIC DIAGRAM



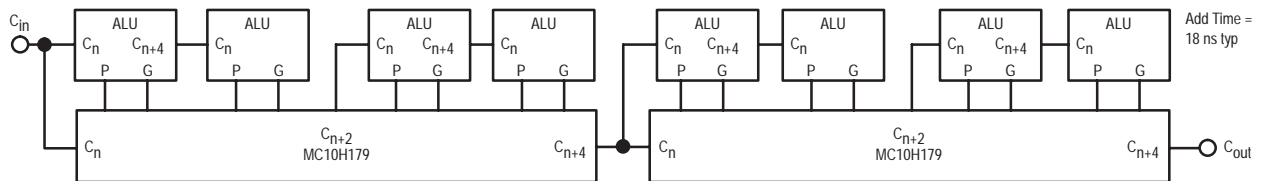
TYPICAL APPLICATIONS

The MC10H179 is a high-speed, low-power, standard MECL complex function that is designed to perform the look-ahead carry function. This device can be used with the MC10H181 4-bit ALU directly, or with the MC10H180 dual arithmetic unit in any computer, instrumentation or digital communication application requiring high speed arithmetic operation on long words.

When used with the MC10H181, the MC10H179 performs a second order or higher look-ahead. Figure 2

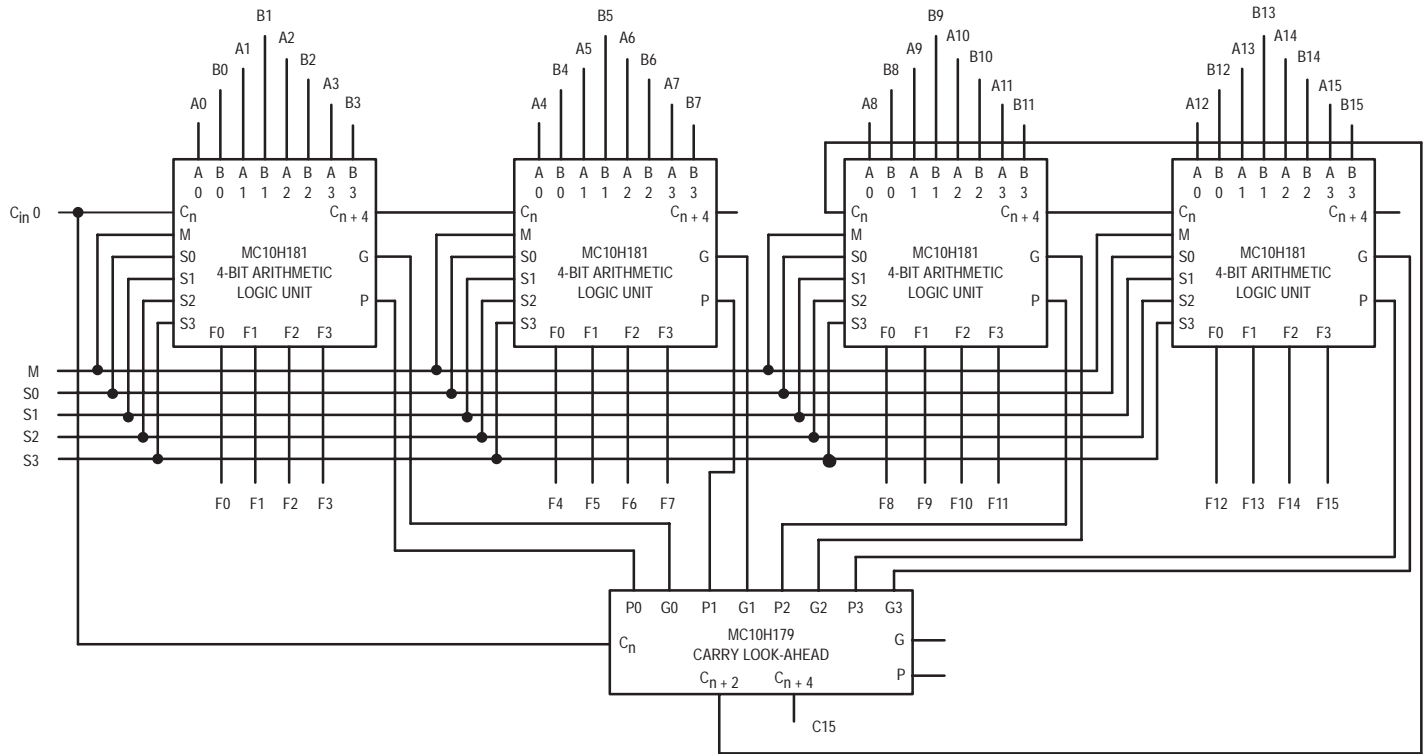
shows a 16-bit look-ahead carry arithmetic unit. Second order carry is valuable for longer binary words. As an example, addition of two 32-bit words is improved from 30 nanoseconds with ripple-carry techniques. A block diagram of a 32-bit ALU is shown in Figure 1. The MC10H179 may also be used in many other applications. It can, for example, reduce system package count when used to generate functions of several variables.

FIGURE 1 – 32-BIT ALU WITH CARRY LOOK-AHEAD



MC10H179

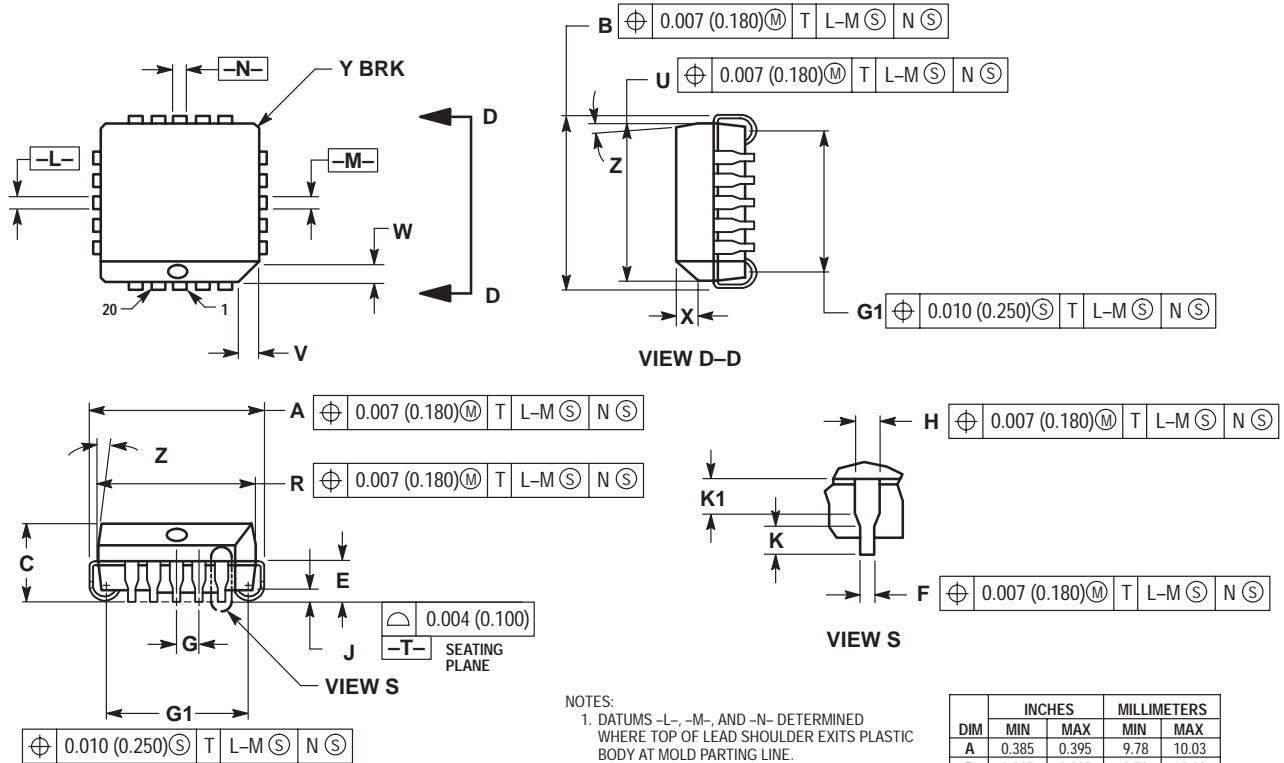
FIGURE 2 – 16-BIT FULL LOOK-AHEAD CARRY ARITHMETIC LOGIC UNIT



MC10H179

PACKAGE DIMENSIONS

PLCC-20
FN SUFFIX
PLASTIC PLCC PACKAGE
CASE 775-02
ISSUE C



NOTES:

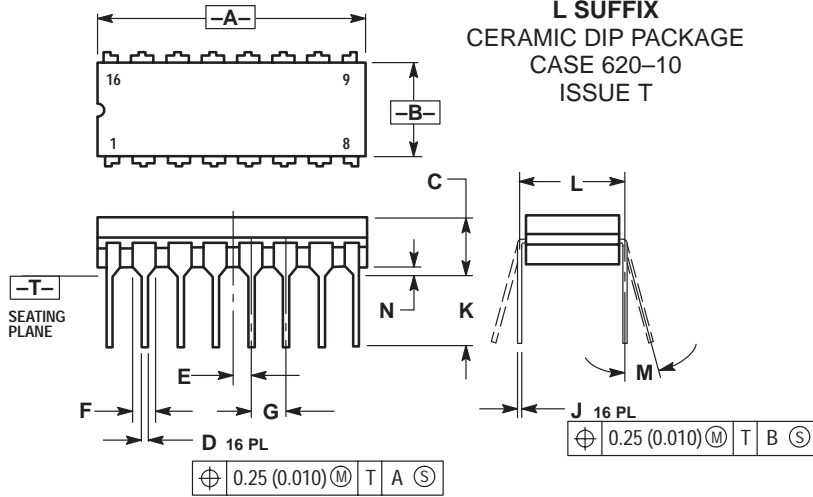
- DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
- DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	2°	10°
G1	0.310	0.330	7.88	8.38
K1	0.040	---	1.02	---

MC10H179

PACKAGE DIMENSIONS

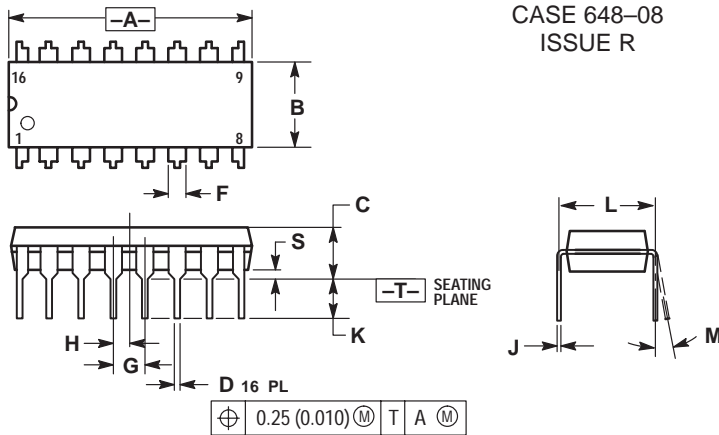
CDIP-16 L SUFFIX CERAMIC DIP PACKAGE CASE 620-10 ISSUE T



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	---	0.200	---	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01


PDIP-16 P SUFFIX PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

Notes

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